

MCPC Compatible USB Port Multimedia Switch

Supports USB, UART, Audio, ID, MIC, and Load Switch

Check for Samples: [TSU6721YFF](#)

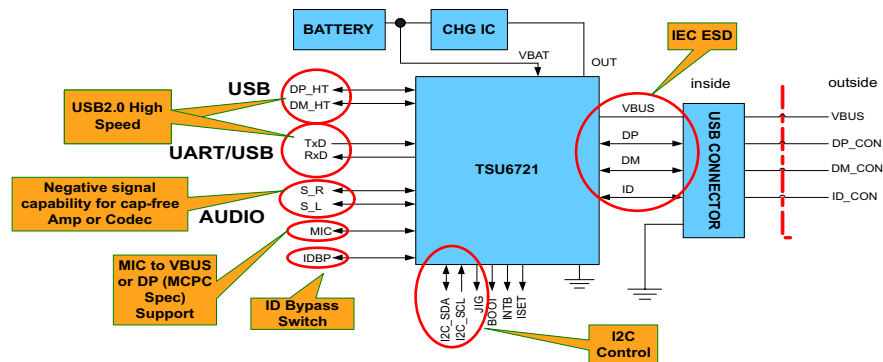
FEATURES

- **Switch Matrix**
 - USB and UART Switch support USB 2.0 HS
 - Audio Switch with Negative Signal Capability
 - ID Bypass Switch
 - VBUS to MIC Switch
 - DP to MIC Switch to Support MCPC
- **Load Switch**
 - 100 mΩ Load Switch
 - OTG Support
 - 28 V VBUS Rating with Over-voltage Protection
 - Programmable Overcurrent Limiter/Protection
- **Charger Detection**
 - USB BCDv1.2 compliant
 - VBUS Detection
 - Data Contact Detection
 - Primary and Secondary Detection
- **Compatible Accessories**
 - USB Chargers (DCP, CDP)
 - Apple Charger
 - USB Data Port
 - Audio Headset with MIC and Remote
 - Docking Support
 - Factory Cable
- **Additional Features**
 - I2C Interface with Host Processor
 - Switches Controlled by Automatic Detection or Manual Control
 - Interrupts Generated for Plug/Unplug
 - Decoupling FET Switch to VBUS Added to Reduce Degradation on MIC Line
 - Support Control Signals used In Manufacturing (JIG, BOOT)
- **ESD Performance Tested Per JESD 22**
 - 4000-V Human-Body Model (A114-B, Class II)
 - 1500-V Charged-Device Model (C101)
- **IEC ESD Performance**
 - ±8 kV Contact Discharge (IEC 61000-4-2) for VBUS/DP/DM/ID to GND

APPLICATIONS

- Cell Phones and Smart Phones
- Tablet PCs
- Digital Cameras and Camcorders
- GPS Navigation Systems
- Micro USB Interface with USB/UART/AUDIO

APPLICATION DIAGRAM



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

For package and ordering information, see the Package Option Addendum at the end of this document.

DESCRIPTION

TSU6721 is a high performance USB port multimedia switch featuring automatic switching and accessory detection. The device connects a common USB port to pass audio, USB data, charging, On The Go (OTG) and factory mode signals. The audio path has negative signal capability includes left (mono/stereo), right (stereo) as well as microphone signals. Furthermore, TSU6721 is compatible with the MCPC specification.

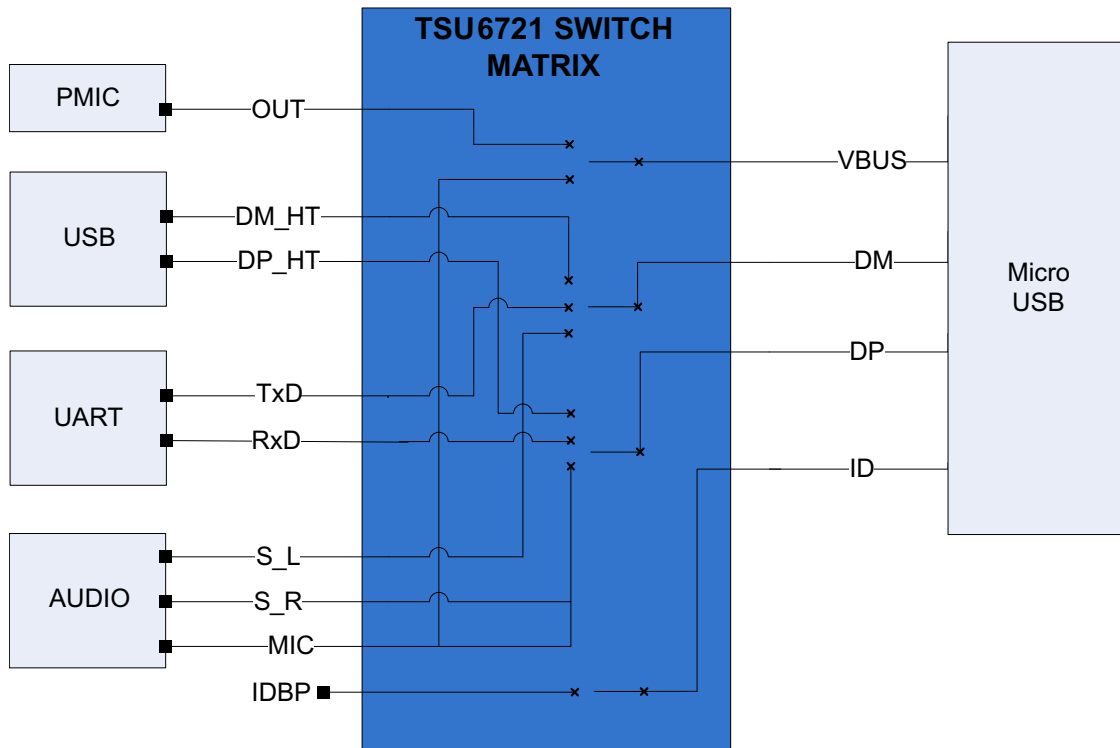
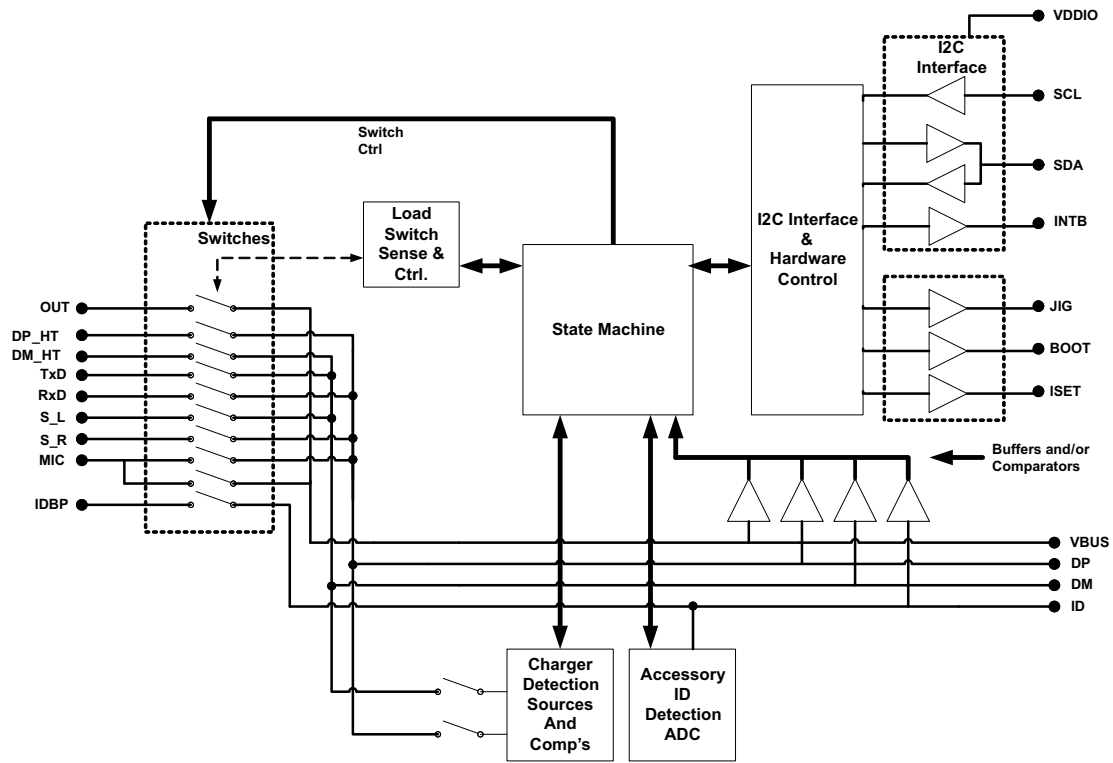
TSU6721 features impedance detection which supports the detection of various accessories that are attached through DP, DM and ID pins of the USB connector. The switch is controlled by automatic switching or manually through I²C.

TSU6721 has an integrated low resistive Load Switch that is used to isolate the charger from the external connector. OverVoltage Protection and programmable OverCurrent Limiter/Protection are additional features included to the Load Switch.

The charger detection satisfies USB charger specification v1.2. In addition to DCP, CDP and SDP, the device also detects Apple Chargers.

Power for this device is supplied through VBAT of the system or through VBUS when attached. TSU6721 supports factory mode testing when a USB/UART JIG cable is used in development and manufacturing.

BLOCK DIAGRAM

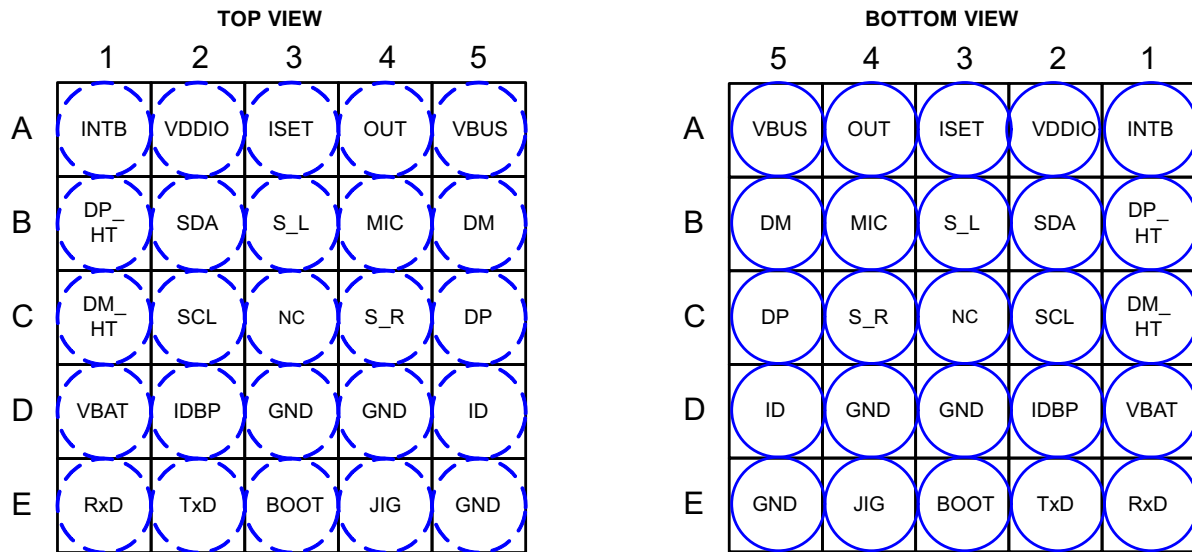


TSU6721YFF

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PIN OUT



PIN FUNCTIONS

BALL NO.	PIN NAME	TYPE	DESCRIPTION
D1	VBAT	–	3.0 – 4.4V Battery supply voltage
A2	VDDIO	–	1.8 ~ 3.3V Logic Supply
A5	VBUS	I	USB connector VBUS
A4	OUT	O	Phone charger output
E5, D3, D4	GND	–	Ground
B1	DP-HT	I/O	USB data plus
C1	DM-HT	I/O	USB data minus
D2	IDBP	I/O	USB ID data
E1	RxD	I/O	UART receive data
E2	TxD	I/O	UART transmit data
C3	NC	–	Not connected internally
B4	MIC	I/O	Microphone signal
C4	S_R	I/O	Stereo headset right sound
B3	S_L	I/O	Mono or stereo headset left sound
C2	SCL	I	I2C clock
B2	SDA	I/O	I2C data
C5	DP	I/O	Common USB connector plus I/O port
B5	DM	I/O	Common USB connector minus I/O port
D5	ID	I/O	Common USB connector ID I/O port
A1	INTB	O	Interrupt signal when peripheral is plugged/unplugged. Push-pull output
A3	ISET	O	High current charger detected. Open-drain output
E4	JIG	O	GPIO factory output. Open-drain output
E3	BOOT	O	GPIO factory output. Push-pull output

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
VBUS	Supply voltage from USB connector	-0.5	28	V	
VBAT	Supply voltage from battery	-0.5	6	V	
VDDIO	Logic supply voltage	-0.5	4.6	V	
VBUS_OUT	Phone charger output	-0.5	7	V	
DP	DP Connector voltage	-0.5	VBAT+0.5	V	
DM	DM Connector voltage	-0.5	VBAT+0.5	V	
ID	ID Connector voltage	-0.5	VBAT+0.5	V	
IDBP	ID Host Side voltage	-0.5	VBAT+0.5	V	
VAUDIO	Switch I/O voltage range	Audio Switch (S_L, S_R)		V	
VMIC		Mic Switch (MIC)			
VUSB/VUART		USB/UART Switch			
VJIG & VISET	JIG and ISET voltage	-0.5	VBAT+0.5	V	
VLOGIC_O	Voltage applied to logic output (SCL, SDA, INTB, BOOT)	-0.5	VDDIO	V	
IBUS	Peak input current on VBUS pin (12.5% duty cycle)		2.0	A	
	Peak input current on VBUS pin (3% duty cycle, 4ms on-time)		2.5		
IBUS_OUT	Peak input current on VBUS pin (12.5% duty cycle)		2.0	A	
	Peak input current on VBUS pin (3% duty cycle, 4ms on-time)		2.5		
I _{ISET} & I _{JIG}	ISET and JIG pins peak current		50	mA	
IK	Analog port diode current	-50	50	mA	
ISW-DC	ON-state continuous switch current	-60	60	mA	
ISW-_ PEAK	ON-state peak switch current	-150	150	mA	
I _{IK}	Digital logic input clamp current	VDDIO < 0		-50	mA
ILOGIC_O	Continuous current through logic output (SCL, SDA, INTB, BOOT)	-50	50	mA	
IGND	Continuous current through GND		100	mA	
Tstg	Storage temperature range	-65	150	°C	

THERMAL IMPEDANCE RATINGS

		VALUE	UNIT
θ_{JA}	Package thermal impedance YFP package	98.8	°C/W

SUMMARY OF TYPICAL CHARACTERISTICS

AMBIENT TEMPERATURE = 25°C	USB/UART PATH	AUDIO PATH	MIC PATH
Number of channels	2	1	1
ON-state resistance (r_{on})	6 Ω / 7 Ω (USB/UART)	2.5 Ω	40 Ω
ON-state resistance match (Δr_{on})	0.2 Ω / 1.5 Ω	0.15 Ω	N/A
ON-state resistance flatness ($r_{on(Flat)}$)	1.4 Ω / 1.4 Ω	0.15 Ω	N/A
Turn-on/Turn-off time (t_{ON}/t_{OFF})	130 μ s / 100 μ s	200 μ s / 100 μ s	260 μ s / 180 μ s
Bandwidth (BW)	510 MHz	450MHz	250 MHz
OFF isolation (O_{ISO})	-26 dB at 250 MHz	-100 dB	-95 dB
Crosstalk (X_{TALK})	-32 dB at 250 MHz	-85 dB	-85 dB
Total Harmonic Distortion (THD)	N/A	0.05%	0.46%
Leakage current ($I_{IO(ON)}$)	50 nA	200 nA	5 nA

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	DESCRIPTION	MIN	MAX	UNITS
V _{BUS}	VBUS voltage	4.0	6.5	V
V _{BAT}	VBAT voltage	3.0	4.4	V
V _{DDIO}	VDDIO voltage	1.65	3.6	V
ID_Cap	ID capacitance		3	nF
USB_I/O	USB path signal range	0	3.6	V
UART_I/O	UART path signal range	0	2.7	V
Audio_I/O	Audio path signal range	-1.5	1.5	V
MIC_I/O	MIC path signal range	0	2.3	V
Temperature	Operating Temperature	-40	85	°C

ELECTRICAL SPECIFICATIONS

DIGITAL SIGNALS – I²C INTERFACE (SCL and SDA)

 T_A = -40°C to 85°C, Typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
V _{DDIO} Logic and I/O supply voltage		1.65	3.6	V
V _{IH} High-level input voltage		V _{DDIO} × 0.7	V _{DDIO}	V
V _{IL} Low-level input voltage		0	V _{DDIO} × 0.3	V
V _{OH} SDA High-level output voltage	I _{OH} = -3 mA	V _{DDIO} × 0.7		V
V _{OL} SDA Low-level output voltage	I _{OL} = 3 mA	0	0.4	V
f _{SCL} SCL frequency			400	kHz

JIG AND ISET FAST-MODE CHARGER OUTPUT (OPEN-DRAIN OUTPUT)

 T_A = -40°C to 85°C, Typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
VOL_JIG Low-level output voltage	I _{OL} = 10 mA, VBAT = 3.0 V	0	0.5	V
VOL_ISET Low-level output voltage	I _{OL} = 10 mA, VBAT = 3.0 V	0	0.7	V

INTB AND BOOT (PUSH-PULL OUTPUT)

 T_A = -40°C to 85°C, Typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -4 mA, VDDIO = 1.65 V	1.16	V _{DDIO}	V
V _{OL} Low-level output voltage	I _{OL} = 4 mA, VDDIO = 1.65 V	0	0.33	V

TOTAL SWITCH CURRENT CONSUMPTION

 T_A = -40°C to 85°C, Typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
IBAT(Standby) VBAT Standby Current Consumption	VBUS = 0 V, Idle state		36	50	μA
IBAT(Operating) VBAT Operating Current Consumption	VBUS = 0 V, USB switches ON		60	80	μA
IVBUS VBUS Operating Current Consumption	No load on OUT pin, VBUS = 5 V		135	155	μA

VBUS CAP SWITCH CHARACTERISTICS

 T_A = -40°C to 85°C, Typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
RDS-VBUSCAP VBUS CAP switch resistance	VBUS = 5 V, I _{OUT} = -20 mA		90		Ω

VOLTAGE PROTECTION

 $T_A = -40^{\circ}\text{C}$ to 85°C , Typical values are at $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{VBUS_UVLO}	V _{BUS} under voltage+	Voltage is Rising, device power-up	3.0	3.25	3.6	V
	V _{BUS} under voltage–	Voltage is Falling, device reset	2.7	3	3.3	
V _{VBUS_VALID}	V _{BUS} interrupt threshold	Voltage is Rising		3.6		V
V _{VBAT_UVLO}	V _{BAT} under voltage+	Voltage is Rising, device power-up	2.5	2.8	3.1	V
	V _{BAT} under voltage–	Voltage is Falling, device reset	2.3	2.6	2.9	

LOAD SWITCH CHARACTERISTICS

 $T_A = -40^{\circ}\text{C}$ to 85°C , Typical values are at $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
RDS-VBUSSWITCH	VBUS switch resistance	VBUS = 5 V, I _{OUT} = 100 mA		90	150	mΩ
t _{ONa}	Turn-ON time automatic mode	RL = 36 Ω, CL = 400 pF, Vbus rising > 3.6V		175		ms
t _{OFFa}	Turn-OFF time automatic mode	RL = 36 Ω, CL = 400 pF, Vbus falling < 3.6V		2.5		ms
t _{ONm}	Turn-ON time manual mode	RL = 36 Ω, CL = 400 pF, From receipt of I2C ACK bit		230		μs
t _{OFFm}	Turn-OFF time manual mode	RL = 36 Ω, CL = 400 pF, From receipt of I2C ACK bit		180		μs
I _{OCP}	Programmable overcurrent protection	V _{BUS} = 5.5V, I2C reg0x22h, Bit [2:0] = 000	0.8	1.0	1.2	A
		V _{BUS} = 5.5V, I2C reg0x22h, Bit [2:0] = 001 (default)	1.3	1.5	1.7	
		V _{BUS} = 5.5V, I2C reg0x22h, Bit [2:0] = 010		2.0		
		V _{BUS} = 5.5V, I2C reg0x22h, Bit [2:0] = 011		2.0		
I _{OCL}	Programmable overcurrent limiter	V _{BUS} = 5.5V, I2C reg0x21h, Bit [7:5] = 000	1.25	1.5	1.75	A
		V _{BUS} = 5.5V, I2C reg0x21h, Bit [7:5] = 001 (default)	1.67	2.0	2.33	
		V _{BUS} = 5.5V, I2C reg0x21h, Bit [7:5] = 010		2.5		
		V _{BUS} = 5.5V, I2C reg0x21h, Bit [7:5] = 011		2.5		
VBUS OVERVOLTAGE PROTECTION (OVP)						
VBUS VOVP	Input overvoltage protection threshold	VBUS increasing from 6 V to 8 V	6.8	7	7.2	V
VBUS t _{OFF(OVP)}	OVP delay	Delay from V _{BUS} > VOVP to Load switch OFF		200		μs
VBUS VHYS-OVP	Hysteresis on OVP	VBUS decreasing from 8 V to 6 V		140		mV
VBUS t _{ON(OVP)}	Recovery time from input overvoltage condition	Delay from V _{BUS} < VOVP-VHYS, to Load switch ON		9		ms
OTP rOTP	OTP Rising Turn Off	Temperature rising until load switch shut off		130		°C
OTP fOTP	OTP Falling Turn On	Temperature falling after OTP shutoff until switch turn on		120		°C

AUDIO SWITCH ELECTRICAL CHARACTERISTICS⁽¹⁾⁽²⁾
 $V_{BAT} = 3.0\text{ V to }4.4\text{ V}$, $V_{DDIO} = 2.8\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$, Typical values are at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG SWITCH							
V_{AUDIO}	Analog signal range			-1.5		3	V
r_{ON}	ON-state resistance	S_L or S_R, DM or DP	$V_I = \pm 0.8\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		2.5	5	Ω
Δr_{ON}	ON-state resistance match between channels		$V_I = 0.8\text{ V}$, $I_I = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		0.15	0.5	Ω
$r_{ON(flat)}$	ON-state resistance flatness		$V_I = \pm 0.8\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		0.15	0.5	Ω
$I_{IO(OFF)}$	V_I or V_O OFF leakage current		$(V_I = -0.8\text{ V}, V_O = 0.8\text{ V})$ or $(V_I = 0.8\text{ V}, V_O = -0.8\text{ V})$, $V_{BAT} = 4.4\text{ V}$, Switch OFF		200	500	nA
$I_{IO(ON)}$	VO ON leakage current		$V_I = \text{OPEN}$, $V_O = -0.8\text{ V}$ or 0.8 V , $V_{BAT} = 4.4\text{ V}$, Switch ON		10	300	nA
DYNAMIC							
t_{ON}	Turn-ON time	From receipt of I ² C ACK bit	V_I or $V_O = V_{BAT}$, $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$		200		μs
t_{OFF}	Turn-OFF time				100		
$C_{I(OFF)}$	VI OFF capacitance		DC bias = 0 V or 1.6 V $f = 10\text{ MHz}$, Switch OFF		5.5		pF
$C_{O(OFF)}$	VO OFF capacitance					10	
$C_{I(ON)}, C_{O(ON)}$	VI, VO ON capacitance		DC bias = 0 V or 1.6 V $f = 10\text{ MHz}$, Switch ON		13		pF
BW	Bandwidth		$R_L = 50\ \Omega$, Switch ON		450		MHz
O_{ISO}	OFF Isolation		$f = 20\text{ kHz}$, $R_L = 50\ \Omega$, Switch OFF		-100		dB
X_{TALK}	Crosstalk		$f = 20\text{ kHz}$, $R_L = 50\ \Omega$		-85		dB
THD	Total harmonic distortion		$R_L = 16\ \Omega$, $C_L = 20\text{ pF}$, $f = 20\text{ Hz} - 20\text{ kHz}$, 1.6 Vpp output		0.05		%
			$R_L = 16\ \Omega$, $C_L = 20\text{ pF}$, $f = 20\text{ Hz} - 20\text{ kHz}$, 3 Vpp output		0.1		%

(1) V_I is equal to the asserted voltage on S_R and S_L pins. V_O is equal to the asserted voltage on DP and DM pins. I_I is equal to the current on the S_R and S_L pins. I_O is equal to the current on the DP and DM pins

(2) Audio Switch is intended for signals to be asserted on S_R/S_L pins and pass to DM/DP

MIC SWITCH ELECTRICAL CHARACTERISTICS⁽¹⁾
 $V_{BAT} = 3.0\text{ V to }4.4\text{ V}$, $V_{DDIO} = 2.8\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$, Typical values are at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
ANALOG SWITCH							
V_{MICIO}	Analog signal range		0	V_{BAT}		V	
r_{ON}	ON-state resistance	MIC, VBUS	$V_I = 2.3\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		40	52	Ω
		MIC, DP	$V_I = 2.3\text{ V}$, $I_I = -5\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		15	25	Ω
$I_{IO(OFF)}$	V_I or V_O OFF leakage current		$V_I = 0.3\text{ V}$, $V_O = 2.3\text{ V}$ or ($V_I = 2.3\text{ V}$, $V_O = 0.3\text{ V}$), $V_{BAT} = 4.4\text{ V}$, Switch OFF		5	500	nA
DYNAMIC							
t_{ON}	Turn-ON time	From receipt of I ² C ACK bit	V_I or $V_O = V_{BAT}$, $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$		260	μs	
t_{OFF}	Turn-OFF time				180		
$C_{I(OFF)}$	VI OFF capacitance	DC bias = 0 V or 3.6 V, $f = 10\text{ MHz}$, Switch OFF		130	pF		
$C_{O(OFF)}$	VO OFF capacitance			10.5	pF		
$C_{I(ON)}$, $C_{O(ON)}$	VI, VO ON capacitance	DC bias = 0 V or 3.6 V $f = 10\text{ MHz}$, Switch ON		140	pF		
BW	Bandwidth, MIC to VBUS		$R_L = 50\ \Omega$, Switch ON		40	MHz	
	Bandwidth, MIC to DP		$R_L = 50\ \Omega$, Switch ON		250		
O_{ISO}	OFF Isolation		$f = 20\text{ kHz}$, $R_L = 50\ \Omega$, Switch OFF		-95	dB	
X_{TALK}	Crosstalk		$f = 20\text{ kHz}$, $R_L = 50\ \Omega$, to audio output		-85	dB	
THD	Total harmonic distortion		$R_L = 600\ \Omega$, $C_L = 20\text{ pF}$, $f = 20\text{ Hz}-20\text{ kHz}$, $V_{in} = 0.1\text{ V}_{pp}$ centered at $V_{BAT}/2$		0.05	0.65	%

(1) V_I is equal to the asserted voltage on VBUS/DP pin. V_O is equal to the asserted voltage on MIC pin. I_I is equal to the current on the VBUS/DP pin. I_O is equal to the current on the MIC pin.

USB & UART SWITCH ELECTRICAL CHARACTERISTICS
 $V_{BAT} = 3\text{ V to }4.4\text{ V}$, $V_{DDIO} = 2.8\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$, Typical values are at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
ANALOG SWITCH							
V_{USBIO}	Analog signal range		0		3.6	V	
V_{UARTIO}	Analog signal range		0		2.7		
r_{ON}	ON-state resistance	DM_HT, DM DP_HT, DP	$V_I = 0\text{ V to }3.6\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		6	11	Ω
		TxD, DM RxD, DP	$V_I = 0\text{ V to }3.6\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		7	14.3	
r_{ON}	ON-state resistance	ID, IDBP	$V_I = 0\text{ V to }3.6\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		30		Ω
Δr_{ON}	ON-state resistance match between channels	DM_HT, DM DP_HT, DP	$V_I = 0.4\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		0.2	1	Ω
		TxD, DM RxD, DP	$V_I = 0.4\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		1.5	3	
$r_{ON(Flat)}$	ON-state resistance flatness	DM_HT, DP_HT, TxD, RxD, DM, DP	$V_I = 0\text{ V to }3.6\text{ V}$, $I_O = -20\text{ mA}$, $V_{BAT} = 3.0\text{ V}$		1.4	3.2	Ω
$I_{IO(OFF)}$	VI or VO OFF leakage current	DM_HT, DP_HT, TxD, RxD, DM, DP	$V_I = 0.3\text{ V}$, $V_O = 2.7\text{ V or }2.7\text{ V}$, $V_O = 0.3\text{ V}$, $V_{BAT} = 4.4\text{ V}$, Switch OFF		45	200	nA
$I_{IO(ON)}$	VO ON leakage current	DM_HT, DP_HT, TxD, RxD, DM, DP	$V_I = \text{OPEN}$, $V_O = 0.3\text{ V or }2.7\text{ V}$, $V_{BAT} = 4.4\text{ V}$, Switch ON		50	200	nA
DYNAMIC							
t_{ON}	Turn-ON time	From receipt of I ² C ACK bit	$V_I \text{ or } V_O = V_{BAT}$, $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$		130		μs
t_{OFF}	Turn-OFF time				100		
$C_{I(OFF)}$	VI OFF capacitance	DC bias = 0 V or 1.6 V, $f = 10\text{ MHz}$, Switch OFF		4		pF	
$C_{O(OFF)}$	VO OFF capacitance			7		pF	
$C_{I(ON)}$, $C_{O(ON)}$	VI, VO ON capacitance	DC bias = 0 V or 3.6 V $f = 10\text{ MHz}$, Switch ON		9		pF	
BW	Bandwidth	$R_L = 50\ \Omega$, Switch ON		510		MHz	
O_{ISO}	OFF Isolation	$f = 240\text{ kHz}$, $R_L = 50\ \Omega$, Switch OFF		-26		dB	
X_{TALK}	Crosstalk	$f = 240\text{ kHz}$, $R_L = 50\ \Omega$		-32		dB	

GENERAL OPERATION

The TSU6721 is a multimedia switch that connects a common USB connector to USB, UART or audio signals. The device also has a MIC switch that connects to either VBUS or DP. It has an integrated load switch to support charging. The load switch has OverVoltage Protection as well as OverCurrent Limiting Protection. In addition, the TSU6721 also has an ID bypass switch to transmit ID signal from the connector to the host. It has an internal FET switch that disconnects the coupling capacitor connected to the VBUS line.

Standby Mode

Standby mode is the default mode upon power up and occurs when no accessory has been detected. During this mode, the VBUS and ID lines are continually monitored through comparators to determine when an accessory is inserted. Power consumption is minimal during standby mode.

Load Switch

The integrated load switch provides both overvoltage/undervoltage and overcurrent limiting protection:

Overvoltage Protection

When the input voltage rises above VOVP, the internal load switch is turned off. The response is very rapid, with the FET turning off in less than $1\mu\text{s}$ $t_{\text{OFF}}(\text{OVP})$. The OVP_EN interrupt bit is set high when an overvoltage condition is detected. When the input voltage returns below VOVP-VHYS_OVP and remains above VUVLO, the VBUS switch is turned on again after a deglitch time of $t_{\text{ON}}(\text{OVP})$. This deglitch time ensures that the input supply has stabilized before turning the switch on. When the OVP condition is cleared, the OVP_OCP_DIS interrupt bit is set high.

Undervoltage Protection

When VBUS is not present and VBAT is less than 2.5V, VBAT and VBUS voltages are below the undervoltage threshold and TSU6721 is powered off.

Overcurrent Limiting Protection

The TSU6721 also provides overcurrent limiting protection. When current increases beyond the I_{OCP} threshold, a time-out delay is initiated. After the delay has expired, and the current is still greater than I_{OCP} , then load switch is disabled. The maximum current that flows through the load switch is controlled by the I_{OCL} limit. This feature provides control on the VBUS charging current and minimizes the chance of internal circuitry damage caused by overcurrent event. The overcurrent level can be programmed through I2C.

Power Supervisor

TSU6721 uses VBAT as the primary supply voltage. VBUS is the secondary supply. VDDIO is used for I2C communication.

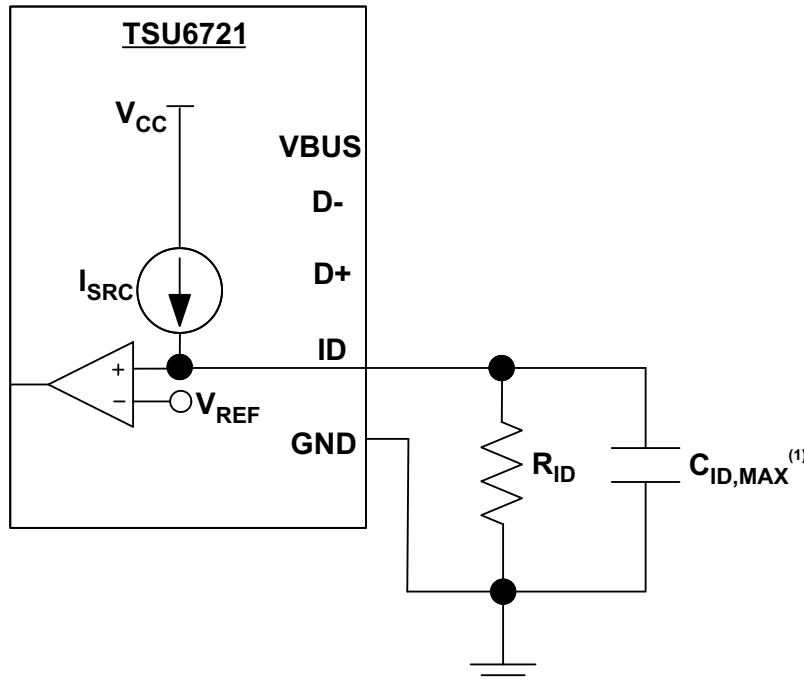
Table 1. Supply Voltage States

VBAT	VBUS	VDDIO	DETECTION	LOAD SWITCH	I2C	COMMENTS
Yes	No	No	Enabled	Not Enabled	Not Enabled	VBAT is supply
Yes	Yes	No	Enabled	Enabled	Not enabled	VBAT is supply. LOAD SWITCH controlled by VBUS
Yes	No	Yes	Enabled	Not Enabled	Enabled	VBAT is supply
Yes	Yes	Yes	Enabled	Enabled	Enabled	VBAT is supply. LOAD SWITCH controlled by VBUS
No	Yes	No	Enabled	Enabled	Not Enabled	VBUS is supply. LOAD SWITCH controlled by VBUS
No	Yes	Yes	Not valid			
No	No	Yes	Not valid			
No	No	No	Power Down Reset			

ACCESSORY ID DETECTION

If VBUS is high and the attachment is a non-compliant charger (see [Table 5](#)), the impedance on the ID pin is then determined. If VBUS is low and an accessory is attached, then an ADC for impedance sensing is used on the ID pin to identify which accessory is attached and/or what kind of remote control key button is pushed.

The TSU6721 features impedance detection for identification of various accessories that might be attached to the micro-USB port. Each accessory is identified by a unique resistor value connected between the ID pin and Ground. During impedance detection a current source is applied to the ID pin. The current source is then applied to the ID pin while an internal voltage reference is incremented till it matches the ID pin voltage. This produces a 5-bit ADC value that corresponds to the ID resistance found. Once an ID resistance is identified, a current source is continuously applied to determine when the resistance is detached.



(1) Maximum ID_Cap capacitance as noted in [RECOMMENDED OPERATING CONDITIONS](#)

Figure 1. Impedance Detection Circuitry

Impedance Buckets for Each Accessory and Remote Control Key Button

In order to implement ID detection, each accessory and remote control key button of audio accessory should contain below ID impedance resistor value which is 1% tolerance accuracy.

Switch Matrix

MCPC accessory table is selected only when MCPC mode is enabled in Control Reg02h. VBUS to OUT Load Switch is enabled anytime VBUS is applied to the USB connector.

Table 2. Accessory ID and Switch States

ACCESSORY	ID	Res (%)	ADC Value	SWITCH STATE					STATUS OUTPUT		
				DP/DM			VBUS	ID	ISET	JIG	BOOT
				USB	UART	Audio	MIC	ID_HT			
OTG	0	–	00000	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF
Video	75	5%	00000	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
MHL	1K	5%	00000	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Send_End Button	2K	10%	00001	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S1 Button	2.604K	5%	00010	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S2 Button	3.208K	5%	00011	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S3 Button	4.014K	5%	00100	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S4 Button	4.82K	5%	00101	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S5 Button	6.03K	5%	00110	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S6 Button	8.03K	5%	00111	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S7 Button	10.03K	5%	01000	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S8 Button	12.03K	5%	01001	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S9 Button	14.46K	5%	01010	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S10 Button	17.26K	5%	01011	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S11 Button	20.5K	5%	01100	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Stereo Headset RC S12 Button	24.07K	5%	01101	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Audio Device Type 3	28.7K	5%	01110	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
Reserved Accessory #1	34K	5%	01111	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Reserved Accessory #2	40.2K	5%	10000	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Reserved Accessory #3	49.9K	5%	10001	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Reserved Accessory #4	64.9K	5%	10010	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Audio Device Type 2	80.27K	5%	10011	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
Phone Powered Device	102K	5%	10100	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF
TTY Converter	121K	5%	10101	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
UART Cable	150K	5%	10110	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF
Type 1 Charger	200K	5%	10111	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
Factory Mode - Boot Off USB	255K	5%	11000	ON	OFF	OFF	OFF	OFF	OFF	ON	OFF
Factory Mode - Boot On USB	301K	5%	11001	ON	OFF	OFF	OFF	OFF	OFF	ON	ON
Audio/Video Cable	365K	5%	11010	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
A/V + VBUS	365K	5%	11010	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
Type 2 Charger	442K	5%	11011	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
Factory Mode - Boot Off UART	523K	5%	11100	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF
Factory Mode - Boot On UART	619K	5%	11101	OFF	ON	OFF	OFF	OFF	OFF	ON	ON
Stereo Audio Device Type 1	1000.07K	10%	11110	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Mono Audio Device Type 1	1002K	10%	11110	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF

Table 3. Accessory ID and Switch States MCPC Mode

ACCESSORY	ID	RES (%)	ADC VALUE	SWITCH STATE					STATUS OUTPUT		
				DP/DM			VBUS	ID	ISET	JIG	BOOT
				USB	UART	AUDIO	MIC	ID_HT			
Send_End_SW	47K	5%	10000	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
			10001			OFF	OFF	OFF			
Send_End_SW with VBUS	47K	5%	10000	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
			10001			OFF	OFF	OFF			
Maintenance	180K	5%	10110	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
			10111			OFF	OFF	OFF			
Mode 1 Stereo	47K + 240K	5%	11000	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
			11001			OFF	OFF	OFF			
Mode 1 Stereo with VBUS	47K + 240K	5%	11000	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
			11001			OFF	OFF	OFF			
Reserved	390K	5%	11010	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
			11011			OFF	OFF	OFF			
Mode 3 Monaural	47K + 510K	5%	11100	DM to S_L; DP to MIC			OFF	OFF	OFF	OFF	OFF
			11101				OFF	OFF	OFF	OFF	
Mode 3 Monaural with VBUS	47K + 510K	5%	11100	DM to S_L; DP to MIC			OFF	OFF	OFF	OFF	OFF
			11101				OFF	OFF	OFF	OFF	
Mode 2 Monaural	47K + 750K	5%	11110	DM to S_L; DP OPEN			ON	OFF	OFF	OFF	OFF
Mode 2 Monaural with VBUS	47K + 750K	5%	11110	DM to S_L; DP OPEN			OFF	OFF	OFF	OFF	OFF

CHARGER DETECTION
Table 4. Chargers Detected and Switch States

ACCESSORY	ID	RES (%)	ADC VALUE	SWITCH STATE					STATUS OUTPUT		
				DP/DM			VBUS	ID	ISET	JIG	BOOT
				USB	UART	AUDIO	MIC	ID_HT			
No ID	–	–	11111	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Apple Charger	–	–	11111	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Non-standard Charger	–	–	11111	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
USB Standard Downstream Port	–	–	11111	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
USB Charging Downstream Port	–	–	11111	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
Dedicated Charging Port	–	–	11111	ON	OFF	OFF	OFF	OFF	ON	ON	OFF

Table 5 lists the configurations of the DP_CON (D+) and DM_CON (D-) that are internal to the various device types.

Table 5. Charger Detection Table

DEVICE TYPE	VBUS	DP_CON (D+)	DM_CON (D-)
Standard Downstream Port	>4 V	Pull-down R 15k to GND	Pull-down R 15k
Charging Downstream Port	>4 V	Pull-down R 15k to GND	$V_{DM_SRC} = 0.6V$
Dedicated Charging Port	>4 V	Short to D-	Short to D+
Apple Charger	>4 V	$2.0 < V_{DP} < 2.8$	$2.0 < V_{DM} < 2.8$
U200	>4 V	$V_{DP} = 1.34$	$V_{DM} = 1.34$
Non-compliant USB Charger Any Device	>4 V	Open	Open

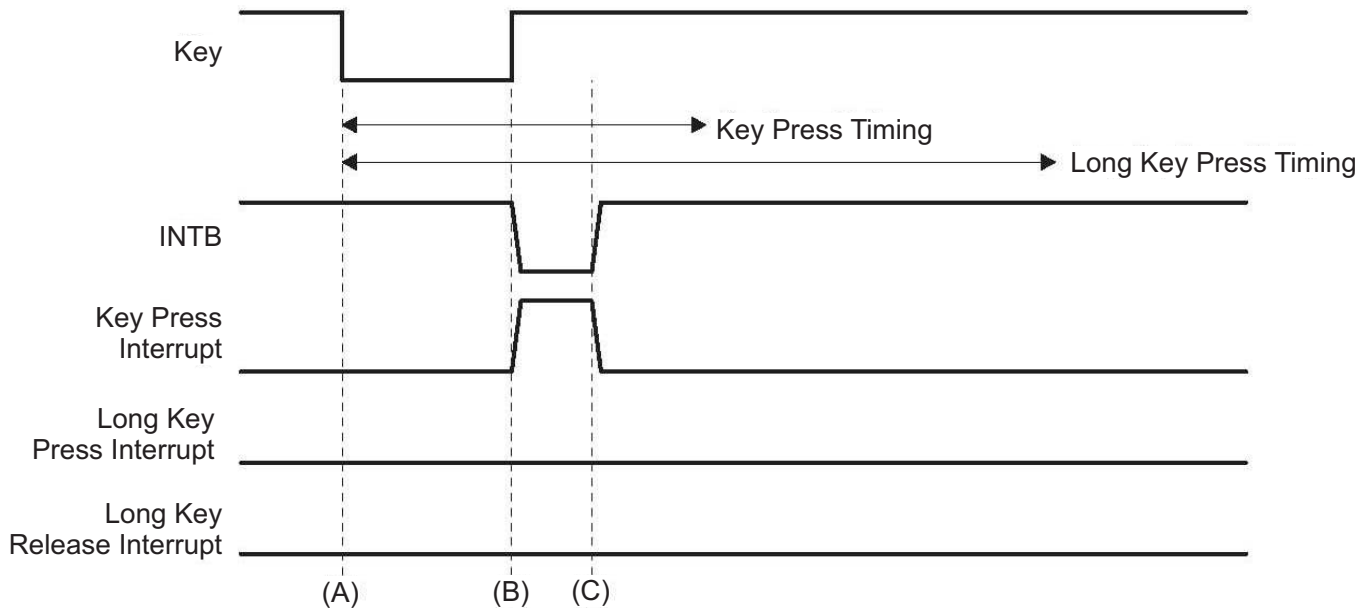
Power-On Reset

When power (from 0 V) is applied to V_{BAT} , an internal power-on reset holds the TSU6721 in a reset condition until V_{BAT} has reached V_{POR} . At that point, the reset condition is released, and the TSU6721 registers and I²C state machine initialize to their default states.

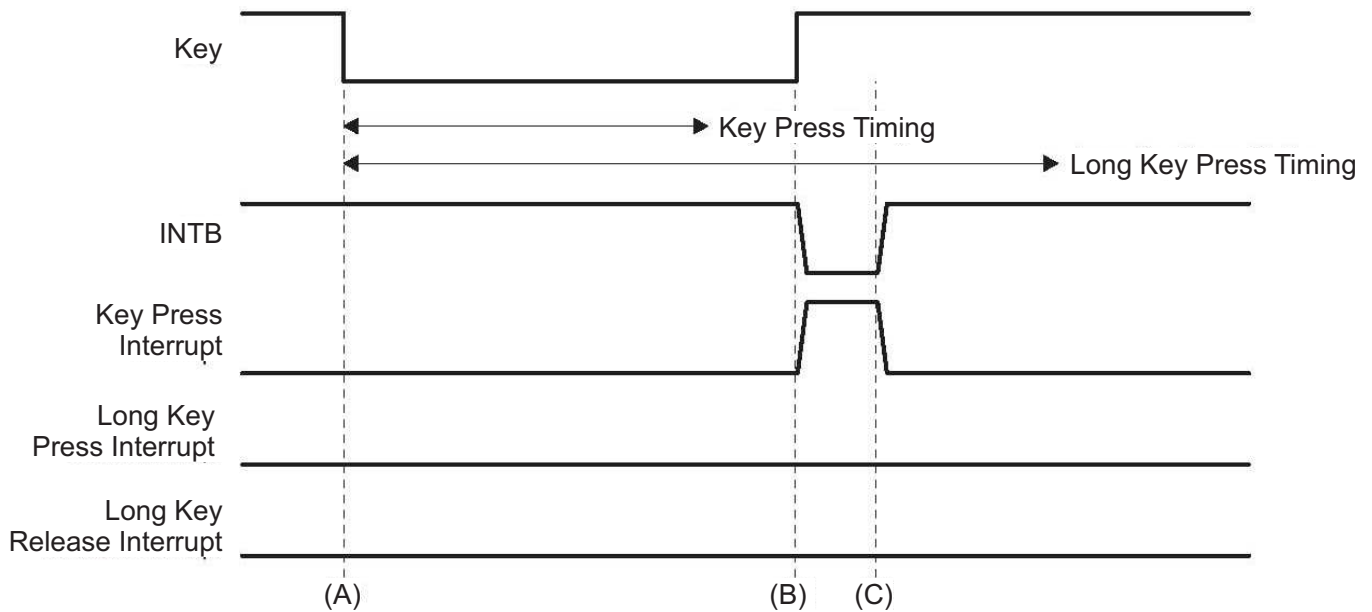
After the initial power-up phase, V_{BAT} must be lowered to below 0.2 V and then back up to the operating voltage (V_{DDIO}) for a power-reset cycle.

Software Reset

The TSU6721 has software a reset feature. Set the reset bit in the I2C register high to reset TSU6721. After resetting, INTB will keep low until INT_Mask bit of Control register (0x02) is cleared.

Key Press Identification


- A. Key press
- B. Released key press → Set KP Interrupt → Set error bit in Button register → INTB pulled low
- C. I²C read of INT register → Clear KP interrupt → INTB goes back high

Figure 2. Short Key Press


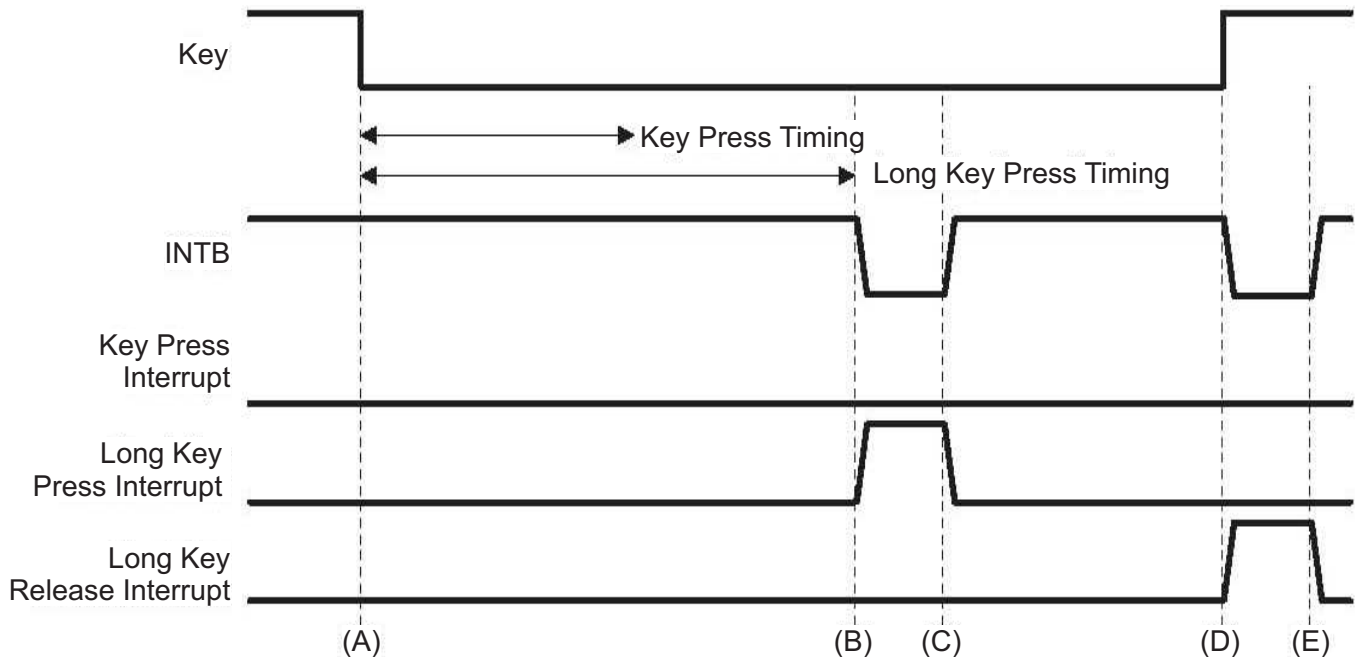
- A. Key press
- B. Released key press → Set KP Interrupt → Set Key (S/E, 1–12) bit in Button register → INTB pulled low .
- C. I²C read of INT register → Clear KP interrupt → INTB goes back high.

Figure 3. Normal Key Press

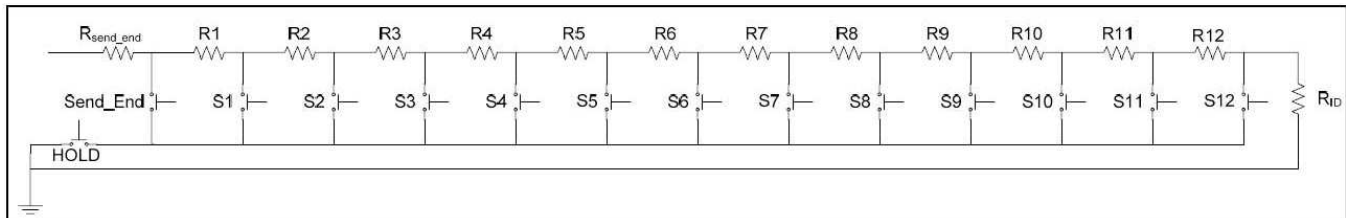


- A. Key press
- B. Long key press timing reached → Set LKP interrupt bit → Set Key (S/E, 1–12) bit in Button register → INTB pulled low
- C. I²C read of INT register → Clear LKP interrupt bit → INTB goes back high
- D. Released key press → Set LKR Interrupt bit → INTB pulled low
- E. I²C read of INT register → Clear LKR interrupt bit → INTB goes back high

Figure 4. Long Key Press



- A. Key press detected when accessory attached
- B. Long key press timing reached → Set SK interrupt bit → Set Key (S/E, 1–12) bit in Button register → INTB pulled low
- C. I²C read of INT register → Clear SK interrupt bit → INTB goes back high
- D. Released key press detected when accessory ID resistor is 1 MΩ → Set SKR Interrupt bit → INTB pulled low
- E. I²C read of INT register → Clear SKR interrupt bit → INTB goes back high

Figure 5. Stuck Key Press

Figure 6. Audio/Remote Controller Accessory

STANDARD I²C INTERFACE DETAILS

The bidirectional I²C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

I²C communication with this device is initiated by the master sending a START condition, a high-to-low transition on the SDA input/output while the SCL input is high (see [Figure 7](#)). After the start condition, the device address byte is sent, MSB first, including the data direction bit (R/W). This device does not respond to the general call address. After receiving the valid address byte, this device responds with an ACK, a low on the SDA input/output during the high of the ACK-related clock pulse.

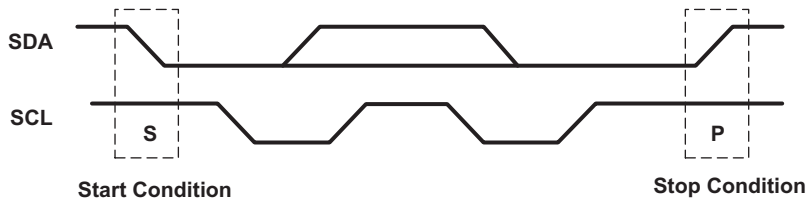


Figure 7. Definition of Start and Stop Conditions

The data byte follows the address ACK. The R/W bit is kept low for transfer from the master to the slave. The data byte is followed by an ACK sent from this device. Data are output only if complete bytes are received and acknowledged. The output data is valid at time (tpv) after the low-to-high transition of SCL, during the clock cycle for the ACK.

On the I²C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (START or STOP) (see Figure 8).

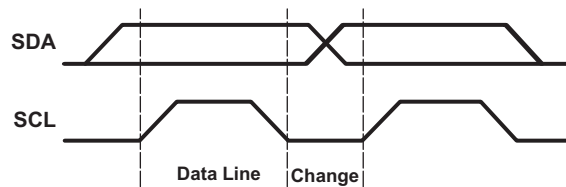


Figure 8. Bit Transfer

A Stop condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see Figure 7).

The number of data bytes transferred between the start and the stop conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit.

A slave receiver that is addressed must generate an ACK after the reception of each byte. The device that acknowledges has to pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see Figure 9). Setup and hold times must be taken into account.

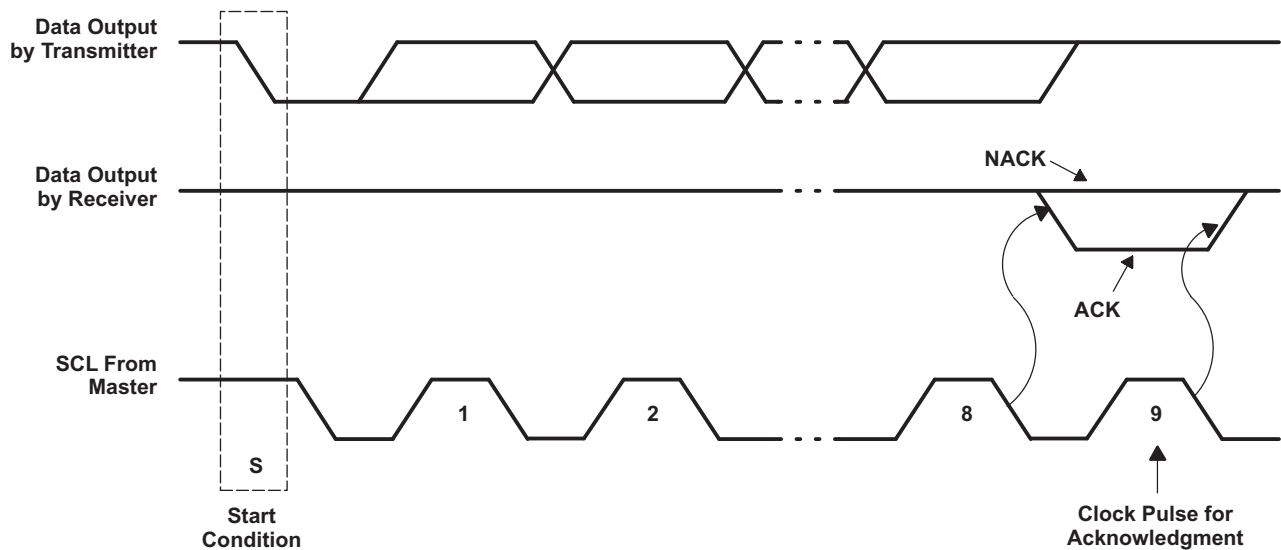


Figure 9. Acknowledgment on I²C Bus

Writes

Data is transmitted to the TSU6721 by sending the device slave address and setting the LSB to a logic 0 (see Figure 10 for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte. The next byte is written to the specified register on the rising edge of the ACK clock pulse.

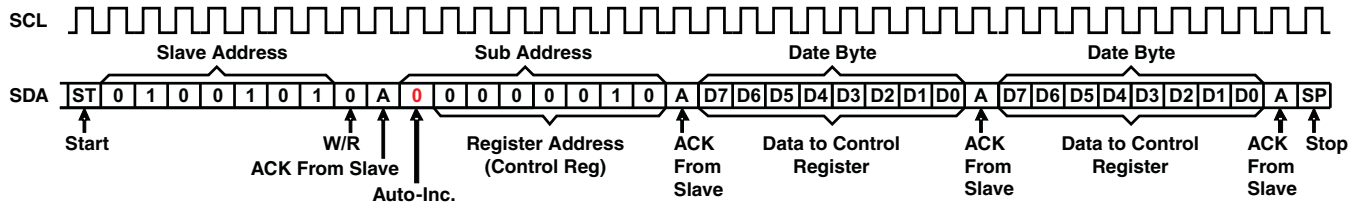


Figure 10. Repeated Data Write to a Single Register

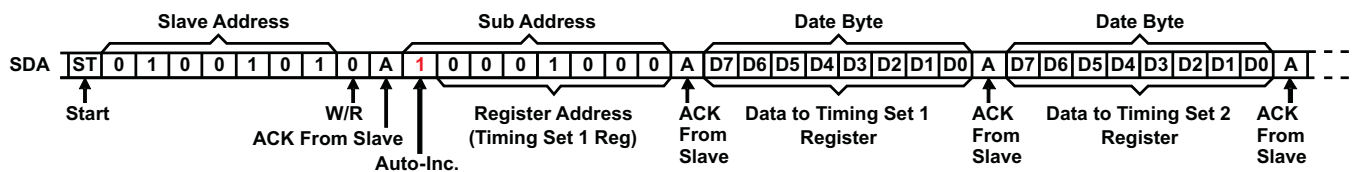


Figure 11. Burst Data Write to Multiple Registers

Reads

The bus master first must send the TSU6721 slave address with the LSB set to logic 0. The command byte is sent after the address and determines which register is accessed. After a restart, the device slave address is sent again but, this time, the LSB is set to logic 1. Data from the register defined by the command byte then is sent by the TSU6721. Data is clocked into the SDA output shift register on the rising edge of the ACK clock pulse. See Figure 12.

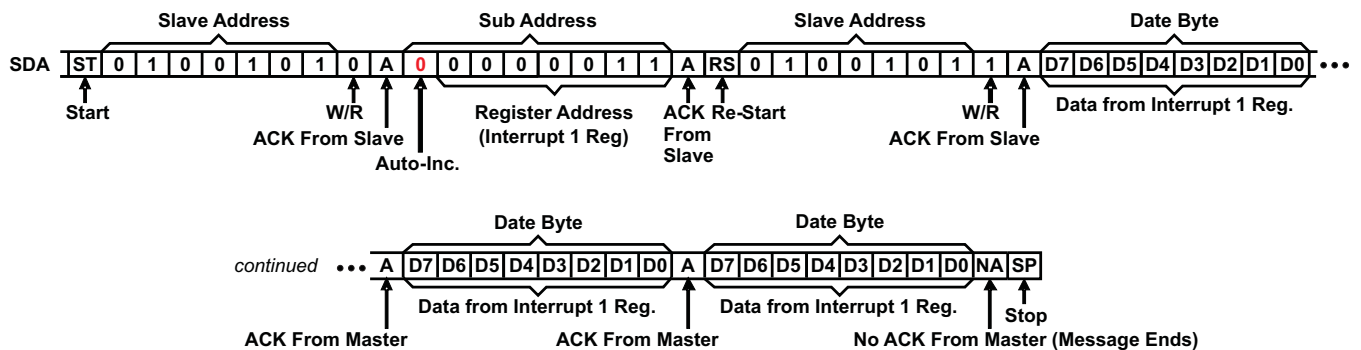


Figure 12. Repeated Data Read from a Single Register – Combined Mode

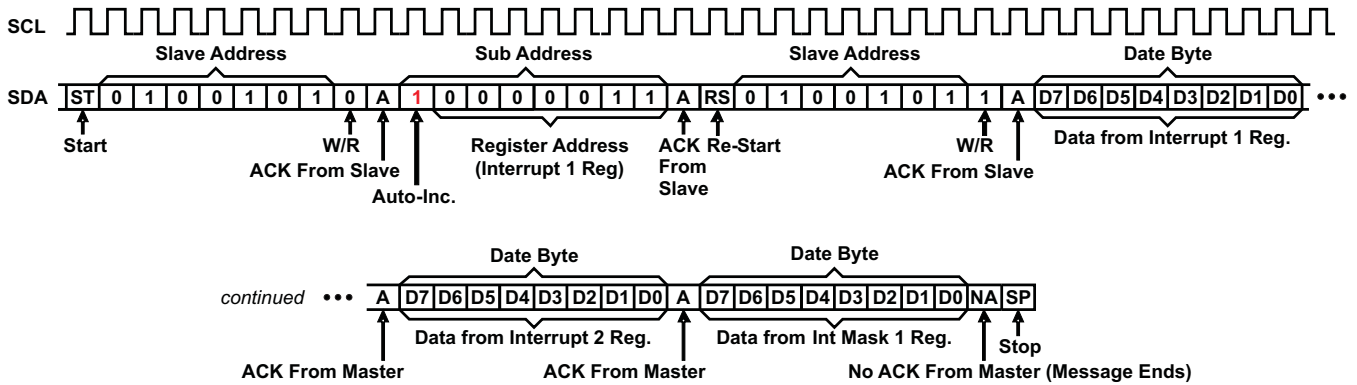


Figure 13. Burst Data Read from Multiple Registers – Combined Mode

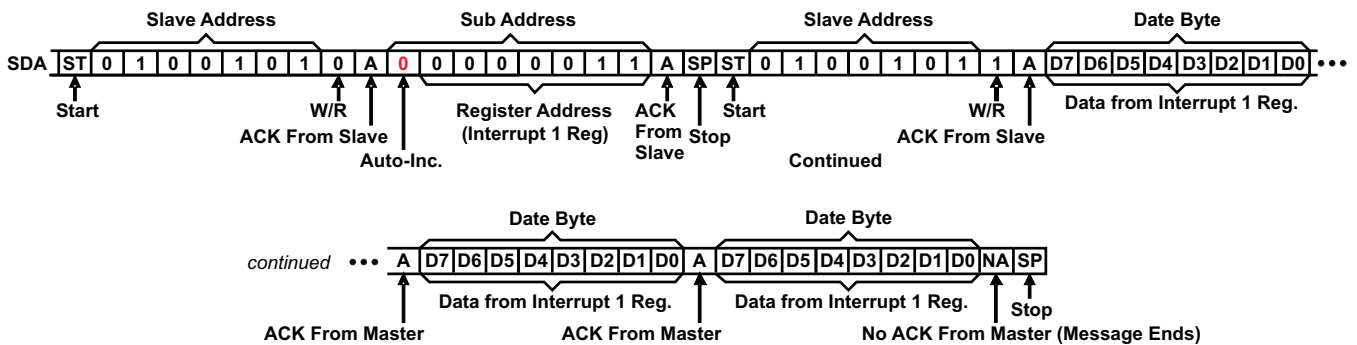


Figure 14. Repeated Data Read from a Single Register – Split Mode

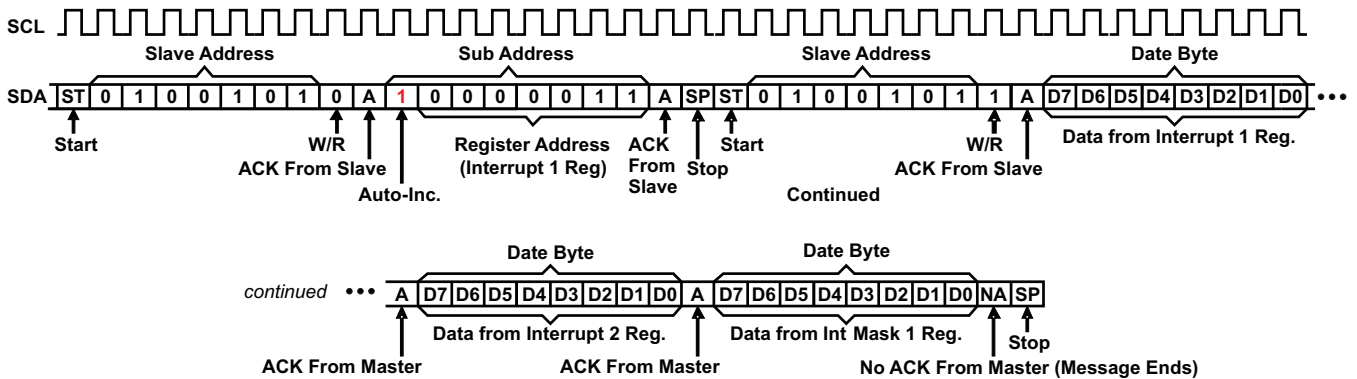


Figure 15. Burst Data Read from Multiple Registers – Split Mode

Notes (Applicable to Figure 10 – Figure 15):

- SDA is pulled low on Ack. from slave or Ack. from master.
- Register writes always require sub-address write before first data byte.
- Repeated data writes to a single register continue indefinitely until Stop or Re-Start.
- Repeated data reads from a single register continue indefinitely until No Ack. from master.
- Burst data writes start at the specified register address, then advance to the next register address, even to the read-only registers. For these registers, data write appears to occur, though no data are changed by the writes. After register 14h is written, writing resumes to register 01h and continues until Stop or Re-Start.
- Burst data reads start at the specified register address, then advance to the next register address. Once register 14h is read, reading resumes from register 01h and continues until No Ack. from master.

I²C REGISTER MAP

ADDRESS	REGISTER	TYPE	RESET VALUE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	
01h	Device ID	R	00010010	Version ID					Vendor ID			
02h	Control	R/W	xx011111			MCPC Mode	Switch Open	Raw Data	Manual S/W	Wait	INT Mask	
03h	Interrupt 1	R	00000000	OVP_OCP_OTP_DIS	OCP_EN	OVP_EN	LKR	LKP	KP	Detach	Attach	
04h	Interrupt 2	R	00000000	VBUS	OTP_EN	CONNECT	Stuck_Key_RCV	Stuck_Key	ADC_Change	Reserved_Attach	A/V_Change	
05h	Interrupt Mask 1	R/W	00000000	OVP_OCP_OTP_DIS	OCP_EN	OVP_EN	LKR	LKP	KP	Detach	Attach	
06h	Interrupt Mask 2	R/W	00000000	VBUS	OTP_EN	CONNECT	Stuck_Key_RCV	Stuck_Key	ADC_Change	Reserved_Attach	A/V_Change	
07h	ADC	R	xxx11111	ADC Value								
08h	Timing Set 1	R/W	00000000	Key Press				Device Sleep				
09h	Timing Set 2	R/W	00000000	Switching Wait				Long Key Press				
0Ah	Device Type 1	R	00000000	USB OTG	DCP	CDP	Type1/Type 2 Charger	UART	USB	Audio Type2	Audio Type1	
0Bh	Device Type 2	R	00000000	Audio Type3	A/V	TTY	PPD	JIG_UART_OFF	JIG_UART_ON	JIG_USB_OFF	JIG_USB_ON	
0Ch	Button 1	R	00000000	7	6	5	4	3	2	1	Send_End	
0Dh	Button 2	R	x0000000		Unknown	Error	12	11	10	9	8	
13h	Manual S/W 1	R/W	00000000	DM Switching			DP Switching			VBUS Switching		
14h	Manual S/W 2	R/W	xxx00000				ISET	BOOT	JIG	ID Switching		
15h	Device Type 3	R	0000x000	Video	U200 Chg	Apple Chg	A/V VBUS		VBUS non-standard	VBUS Debounce	MHL	
1Bh	Reset	W	xxxxxxx0								Reset	
20h	Timer Setting	R/W	00010101	ISET Enable Time	Load Switch Enable Time	BCDv1.2 Timer			ADC Start Time			
21h	OCL/OCP Setting 1	R/W	001010x1	OCL Protection Level Setting			OCP Timeout Delay Setting				BCDv1.2 Enable	
22h	OCL/OCP Setting 2	R/W	xxx11001				OC Enable		OCP Protection Level Setting			
23h	Device Type 4	R/W	xxxxx111						MCPC ID Resistor Value			

Notes:

1. Do not use blank register bits.
2. Write "0" to the blank register bits.
3. Values read from the blank register bits are not defined and invalid.
4. When reading I2C table after an interrupt first read register Interrupt 1 (03h) followed by Interrupt 2 (04h).
5. Interrupt 1 (03h) and Interrupt 2 (04h) should not be read when INT Mask = 0.
6. I2C should not be accessed within 5 ms of device power-up.

Slave Address

NAME	SIZE (BITS)	DESCRIPTION									
		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0		
Slave address	8	0	1	0	0	1	0	1	R/W		

Device ID

Address: 01h

Reset Value: 00010010

Type: Read

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
2-0	Vendor ID	3	A unique number for vendor 010b for Texas Instruments
7-3	Version ID	5	A unique number for chip version 00010b for TSU6721

Control

Address: 02h

Reset Value: xx011111

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	INT Mask	1	0: Unmask interrupt 1: Mask interrupt
1	Wait	1	0: Wait until host re-sets this bit(WAIT bit) high 1: Wait until Switching timer is expired defined in Timing Set 2
2	Manual S/W	1	0: Manual Switching 1: Automatic Switching
3	RAW Data	1	0: Report the status changes on ID to Host 1: Don't report the status changes on ID
4	Switch Open	1	0: Open all Switches (Including load switch) 1: Automatic Switching by accessory status
5	MCPC Mode	1	0: Non-MCPC Mode 1: MCPC Mode
7-6	Unused	2	

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Interrupt 1

Address: 03h

Reset Value: 00000000

Type: Read and Clear

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	Attach	1	1: Accessory is attached
1	Detach	1	1: Accessory is detached
2	KP	1	1: Key press
3	LKP	1	1: Long key press
4	LKR	1	1: Long key release
5	OVP_EN	1	1: OVP enabled
6	OCP_EN	1	1: OCP enabled
7	OVP_OCP_OTP_DISABLE	1	1: OVP_OCP_OTP disabled (device is out of OVP, OCP or OTP)

Interrupt 2

Address: 04h

Reset Value: 00000000

Type: Read and Clear

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	A/V_Change	1	1: Accessory Change is detected when A/V cable is attached
1	Reserved_Attach	1	1: Reserved Device is attached
2	ADC_Change	1	1: ADC value is changed when RAW data is enabled
3	Stuck_Key	1	1: Stuck Key is detected
4	Stuck_Key_RCV	1	1: Stuck Key is recovered
5	Connect	1	1: Switch is connected (closed)
6	OTP_EN	1	1: Over Temperature Protection enabled
7	VBUS	1	1: VBUS detected

Interrupt Mask 1

Address: 05h

Reset Value: 00000000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	Attach	1	0: Unmask Attach Interrupt 1: Mask Attach Interrupt
1	Detach	1	0: Unmask Key press Interrupt 1: Mask Detach Interrupt
2	KP	1	0: Unmask Key press Interrupt 1: Mask Key press Interrupt
3	LKP	1	0: Unmask Long key press Interrupt 1: Mask Long key press Interrupt
4	LKR	1	0: Unmask Long key release Interrupt 1: Mask Long key release Interrupt
5	OVP_EN	1	0: Unmask OVP_EN Interrupt 1: Mask OVP_EN Interrupt
6	OCP_EN	1	0: Unmask OCP_EN Interrupt 1: Mask OCP_EN Interrupt
7	OVP_OCP_OTP_DIS	1	0: Unmask OVP_OCP_OTP_DIS Interrupt 1: Mask OVP_OCP_OTP_DIS Interrupt

Interrupt Mask 2

Address: 06h

Reset Value: 00000000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	A/V_Change	1	0: Unmask A/V_Change Interrupt 1: Mask A/V_Change Interrupt
1	Reserved_Attach	1	0: Unmask Reserved_Attach Interrupt 1: Mask Reserved_Attach Interrupt
2	ADC_Change	1	0: Unmask ADC_Change Interrupt 1: Mask ADC_Change Interrupt
3	Stuck_Key	1	0: Unmask Stuck_Key Interrupt 1: Mask Stuck_Key Interrupt
4	Stuck_Key_RCV	1	0: Unmask Stuck_Key_RCV Interrupt 1: Mask Stuck_Key_RCV Interrupt
5	Connect	1	0: Unmask Connect Interrupt 1: Mask Connect Interrupt
6	OTP_EN	1	0: Unmask OTP_EN Interrupt 1: Mask OTP_EN Interrupt
7	VBUS	1	0: Unmask VBUS Interrupt 1: Mask VBUS Interrupt

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ADC Value

Address: 07h

Reset Value: xxx11111

Type: Read

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
4-0	ADC value	5	ADC value read from ID
7-5	Unused	3	

Timing Set 1

Address: 08h

Reset Value: 00000000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
3-0	Device Sleep	4	Device Sleep duration
7-4	Key press	4	Normal key press duration

Timing Set 2

Address: 09h

Reset Value: 00000000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
3-0	Long key press	4	Long key press duration
7-4	Switching wait	4	Waiting duration before switching

Time Table

SETTING VALUE	DEVICE SLEEP	KEY PRESS	LONG KEY PRESS	SWITCHING WAIT(1)
0000	50 ms	100 ms	300 ms	10 ms
0001	100 ms	200 ms	400 ms	30 ms
0010	150 ms	300 ms	500 ms	50 ms
0011	200 ms	400 ms	600 ms	70 ms
0100	300 ms	500 ms	700 ms	90 ms
0101	400 ms	600 ms	800 ms	110 ms
0110	500 ms	700 ms	900 ms	130 ms
0111	600 ms	800 ms	1000 ms	150 ms
1000	700 ms	900 ms	1100 ms	170 ms
1001	800 ms	1000 ms	1200 ms	190 ms
1010	900 ms	–	1300 ms	210 ms
1011	1000 ms	–	1400 ms	–
1100	–	–	1500 ms	–
1101	–	–	–	–
1110	–	–	–	–
1111	–	–	–	–

Device Type 1

Address: 0Ah

Reset Value: 00000000

Type: Read

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	Audio type 1	1	Audio device type 1
1	Audio type 2	1	Audio device type 2
2	USB	1	USB host
3	UART	1	UART
4	Type1/Type2	1	Type1/Type2 Charger
5	CDP	1	Charging Downstream Port (USB Host Hub Charger)
6	DCP	1	Dedicated Charging Port
7	USB OTG	1	USB on-the-go device

Device Type 2

Address: 0Bh

Reset Value: 00000000

Type: Read

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	JIG_USB_ON	1	Factory mode cable
1	JIG_USB_OFF	1	Factory mode cable
2	JIG_UART_ON	1	Factory mode cable
3	JIG_UART_OFF	1	Factory mode cable
4	PPD	1	Phone-powered device
5	TTY	1	TTY converter
6	A/V	1	A/V Cable
7	Audio Type 3	1	Audio device type 3

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Button 1

Address: 0Ch

Reset Value: 00000000

Type: Read and Clear

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	Send_End	1	Send_End key is pressed
1	1	1	Number 1 key is pressed
2	2	1	Number 2 key is pressed
3	3	1	Number 3 key is pressed
4	4	1	Number 4 key is pressed
5	5	1	Number 5 key is pressed
6	6	1	Number 6 key is pressed
7	7	1	Number 7 key is pressed

Button 2

Address: 0Dh

Reset Value: x0000000

Type: Read and Clear

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	8	1	Number 8 key is pressed
1	9	1	Number 9 key is pressed
2	10	1	Number 10 key is pressed
3	11	1	Number 11 key is pressed
4	12	1	Number 12 key is pressed
5	Error	1	Error key is pressed
6	Unknown	1	Unknown key is pressed
7	Unused	1	

Manual S/W 1

Address: 13h

Reset Value: 00000000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
1-0	V _{BUS} Switching	2	00: Open all switch 01: V _{BUS} is connected to V _{BUS_OUT} (charger) 10: V _{BUS} is connected to MIC
4-2	DP Switching	3	000: Open all switch 001: DP is connected to DP_HT of USB port 010: DP is connected to S_R 011: DP is connected to RxD of UART 100: Reserved 101: DP is connected to MIC 110-111: Reserved
7-5	DM Switching	3	000: Open all switch 001: DM is connected to DM_HT of USB port 010: DM is connected to S_L 011: DM is connected to TxD of UART 100-111: Reserved

Manual S/W 2

Address: 14h

Reset Value: xxx00000

Type: Read/Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
1-0	ID Switching	2	00: Open all switch 01: Reserved 10: ID is connected to IDBP 11: Reserved
2	JIG	1	0: Low (JIG OFF) 1: High (JIG ON)
3	BOOT	1	0: Low (BOOT OFF) 1: High (BOOT ON)
4	ISET	1	0: Low (ISET OFF) 1: High (ISET ON)
7-5	Unused	3	

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Device Type 3

Address: 15h

Reset Value: x000x000

Type: Read

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	MHL	1	MHL device detected
1	VBUS Debounce	1	This bit goes high after the 8ms VBUS debounce time
2	VBUS Non-Standard	1	A non-standard charger device detected. This bit goes high after BCDv1.2 timer expires
3	Unused	1	
4	A/V VBUS	1	A/V Dock with VBUS connected
5	Apple Chg	1	Apple Charger
6	U200 Chg	1	U200 Charger
7	Video	1	75 Ohm video cable

Reset

Address: 1Bh

Reset Value: xxxxxx0

Type: Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	Reset	1	Manual reset on device
7-1	Unused	6	

Timer Setting

Address: 20h

Reset Value:00010101

Type: Read and Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
2-0	ADC Start Time	3	000: 1ms 001: 2ms 010: 4ms 011: 8ms 100: 12ms 101: 16ms 110: 20ms 111: 24ms
5-3	BCDv1.2 Timer	3	000: 0.6s 001: 1.2s 010: 1.8s 011: 2.4s 100: 3s 101: 3.6s
6	Load Switch Enable Time	1	0: 150ms 1: 450ms
7	ISET Enable Time	1	0: 40ms 1:100ms

OCP Setting 1

Address: 21h

Reset Value:001010x1

Type: Read and Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
0	BCDv1.2 Enable	1	0: disabled 1: enabled
1	Unused	1	
4-2	OCP Timeout Delay	3	000: 1ms 001: 2ms 010: 4ms 011: 8ms 100: 12ms 101: 16ms
7-5	OCL Current Limiter Setting	1	000: 1.5A 001: 2.0A 010: 2.5A 011: 2.5A

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OCP Setting 2

Address: 22h

Reset Value: xxx11001

Type: Read and Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
2-0	OCP Protection Level Setting	3	000: 1.0A 001: 1.5A 010: 2.0A 011: 2.0A
4-3	OC Enable	2	00: OCP & OCL disabled 01: OCP disabled & OCL enabled 10: Unused 11: OCP & OCL enabled
7-5	Unused	3	

Device Type 4

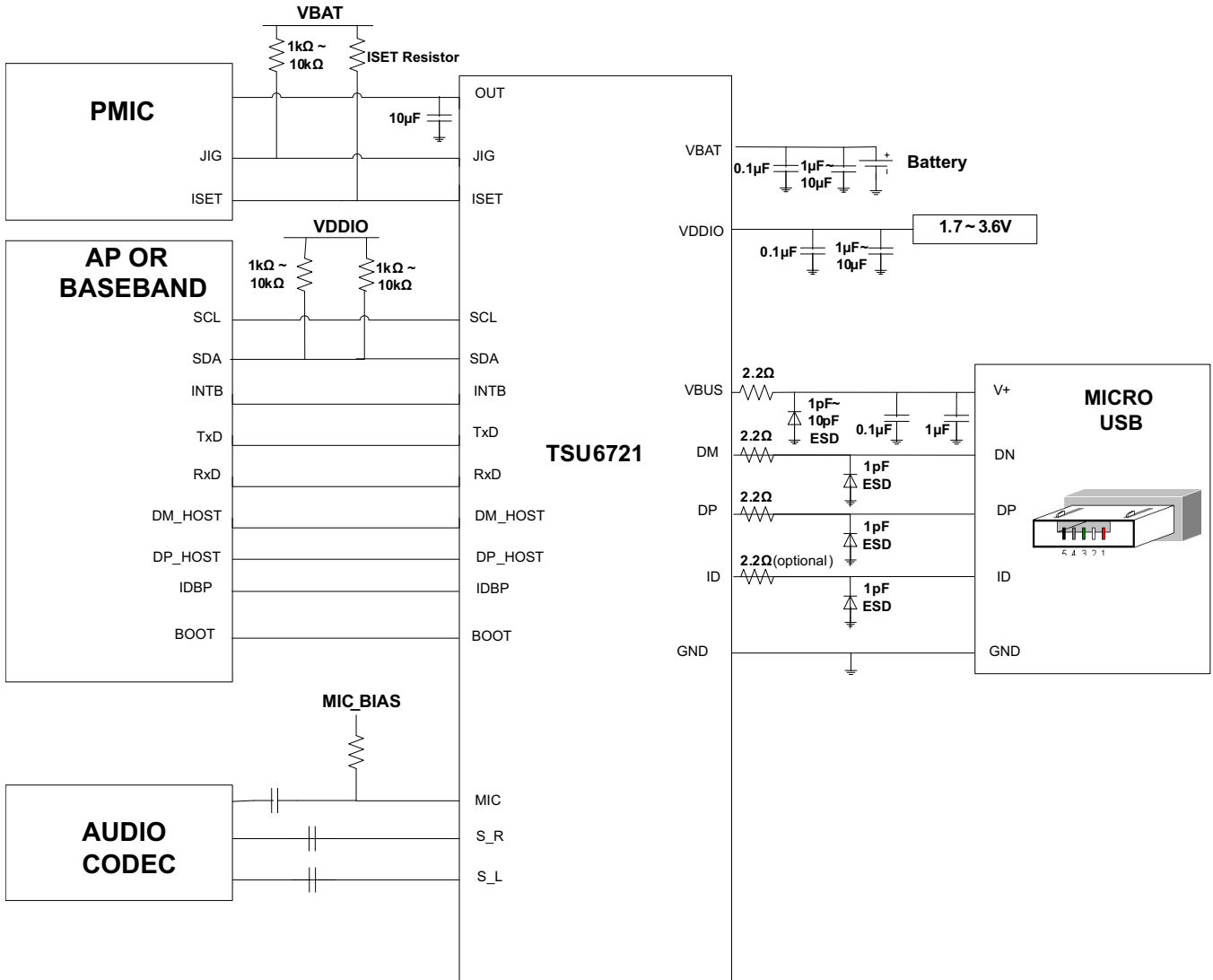
Address: 23h

Reset Value: xxxxx111

Type: Read and Write

BIT NO.	NAME	SIZE (BITS)	DESCRIPTION
2-0	MCPC ID Resistor Value	3	000: 47k ohms 001: 180k ohms 010: 390k ohms 011: 287k ohms (Mode 1) 100: 557k ohms (Mode 3) 101: 797k ohms (Mode 2) 110: Error 111: Reset
7-3	Unused	5	

APPLICATION SCHEMATIC



CRITICAL COMPONENTS

PIN NAME	PIN NUMBER	CRITICAL COMPONENT
VBUS	A5, B5	2.2 Ω
VDDIO	D3	1 μF –10 μF
		0.1 μF
VBAT	C3	1 μF –10 μF
		Battery
		0.1 μF
JIG	E3	1 k Ω –10 k Ω
MIC	B3	2.2 k Ω
		10 μF
ISET	A2	Resistor determined by Battery Charger
S_R	D4	220 μF ⁽¹⁾
S_L	C4	220 μF ⁽¹⁾
OUT	A4, B4	10 μF
SCL	A1	1 k Ω –10 k Ω
SDA	B1	1 k Ω –10 k Ω
DM	C5	2.2 Ω
		ESD Protection Diode
DP	D5	2.2 Ω
		ESD Protection Diode
ID	E5	2.2 Ω ⁽¹⁾
		ESD Protection Diode

(1) Optional Components

SCHEMATIC GUIDELINES

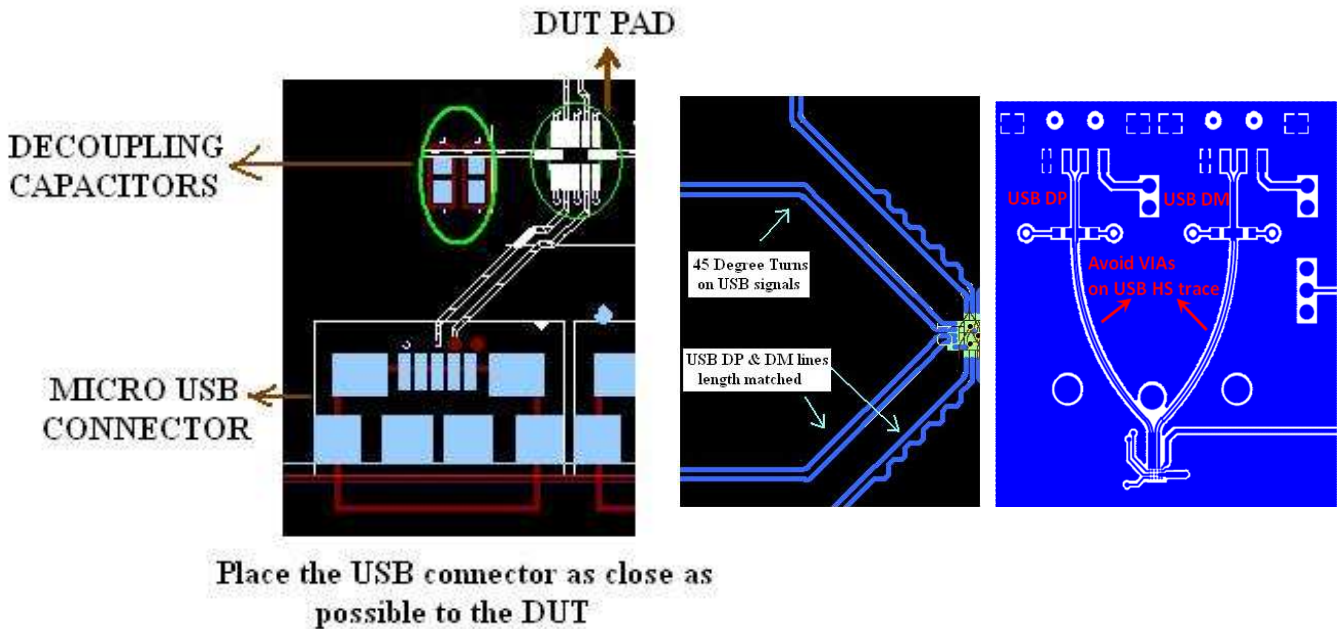
- VBUS, VDDIO, and VBAT require decoupling capacitors to reduce noise from circuit elements. The capacitors act as a shunt to block off the noise. The 0.1 μF capacitor smoothes out high frequencies and has a lower series inductance. The 1 μF –10 μF and 1 μF capacitors smooth out the lower frequencies and have a much higher series inductance. Placing both decoupling capacitors will provide better load regulation across the frequency spectrum.
- OUT requires a 10 μF load capacitor to prevent sudden increases of voltage on the pin during charging
- JIG is an open-drain output and therefore requires a 1k Ω ~ 10k Ω pull-up resistor to VBAT
- ISET is an open drain output. It can be used by the battery charger to set the input current limit with a series resistor (for example 75 Ω determined by the charger)
- SCL and SDA require 1k Ω ~ 10k Ω pull-up resistors to VDDIO to prevent floating inputs
- Depending on the codec used, S_R and S_L may require DC blocking capacitors as high as 220 μF . The capacitor might not be needed if the codec has the capability to provide ground centered signals.
- Mic requires a 2.2k Ω pull-up resistor to MIC_BIAS to provide DC bias for the microphone. Additionally the 10 μF capacitor is required to block the DC signals from MIC_BIAS to the Audio Codec
- VBUS, DM and DP are recommended to have an external resistor 2.2 Ω to provide extra ballasting to protect the chip and internal circuitry
 - For ID, if there is less stress on the ID pin then the external 2.2 Ω resistor is optional

9. DDM, DP, and ID are rated for 6kV IEC contact discharge protection. To prevent failure in case of an IEC contact discharge of 8kV or greater, it is recommended to have an external ESD Protection Diode (~1pF of capacitance allowed) rated for greater than 8kV IEC protection. It is also recommended to have an external ESD Protection Diode to prevent DP and DM from failure in the event of EOS related to electrical surge propagated downstream from the AC power supply
10. VBUS is rated for 6kV IEC contact discharge protection. To prevent failure in case of an IEC contact discharge of 8kV or greater, it is recommended to have an external ESD Protection Diode (~1pF of capacitance allowed) rated for greater than 8kV IEC protection. It is also recommended to have an external ESD Protection Diode to prevent VBUS from failure in the event of EOS related to electrical surge propagated downstream from the AC power supply.

PCB ROUTING GUIDELINES

Routing Guidelines for USB Signal Integrity

1. All the USB lines DP_CON, DM_CON, DP_HT, DM_HT, TxD and RxD
 - (a) Must have 45Ω single ended characteristic impedance
 - (b) Must have 90Ω differential ended impedance
 - (c) To fulfill USB 2.0 requirements
2. TSU6721 location
 - (a) Close to the USB connector as possible
 - (b) The distance between the USB controller and the device less than 1 inch
 - (c) Shorter length of the trace will reduce effect of stray noise and radiate less EMI
3. Minimize use of VIAs for USB related signals
 - (a) Differential transmission lines should be matched as close as possible
 - (b) No VIAs for optimum USB2.0 performance



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TSU6721YFFR	ACTIVE	DSBGA	YFF	25	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TSU6721	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

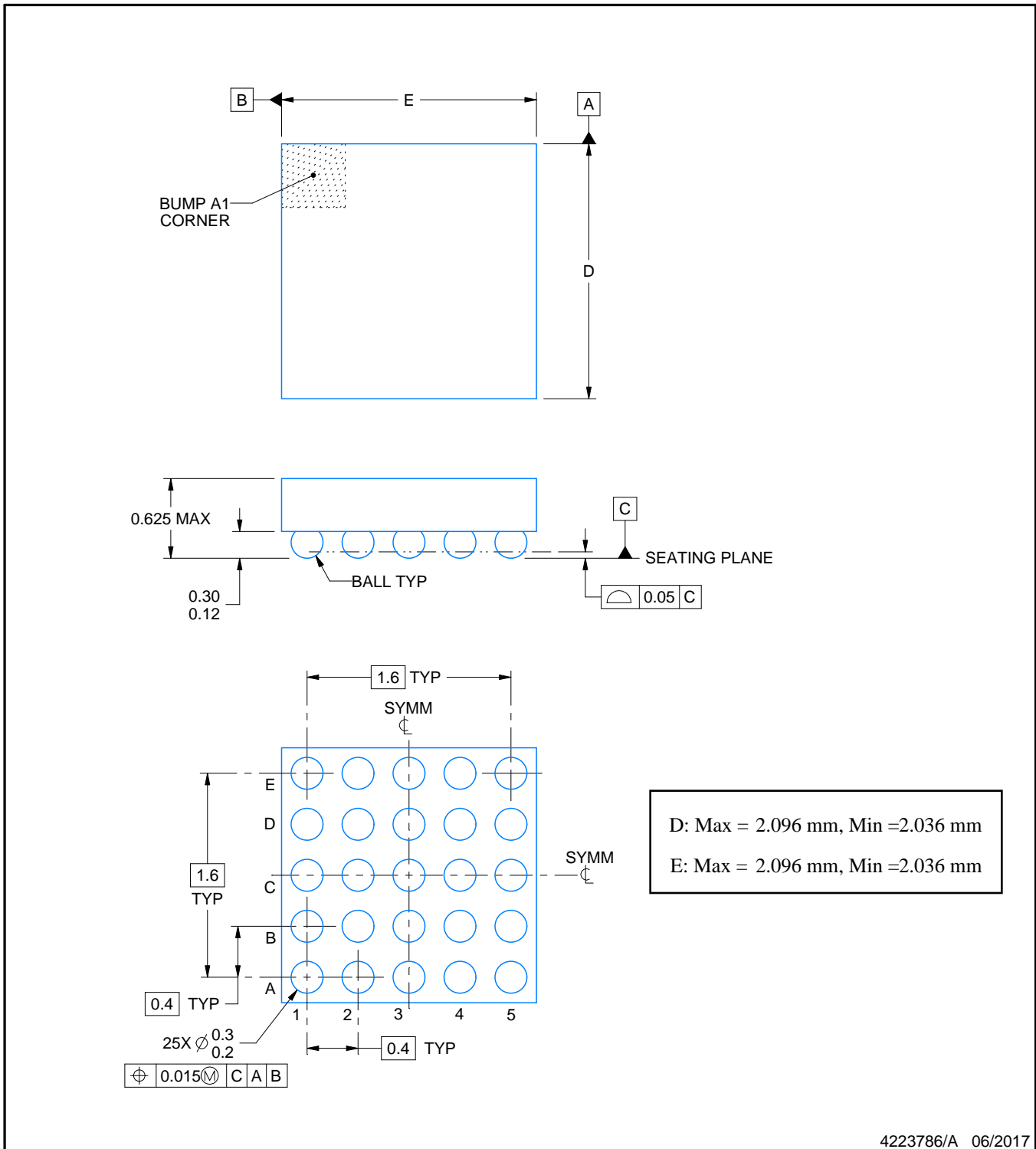
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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NOTES:

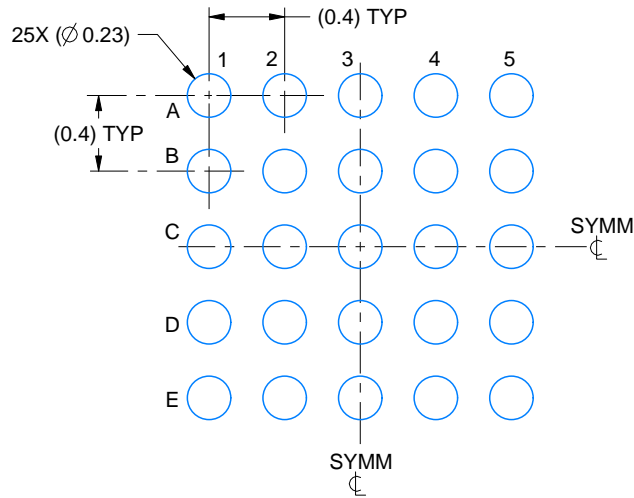
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

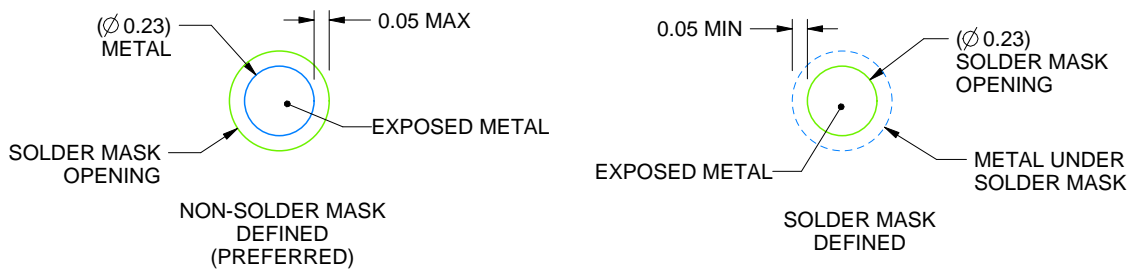
YFF0025

DSBGA - 0.625 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:25X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

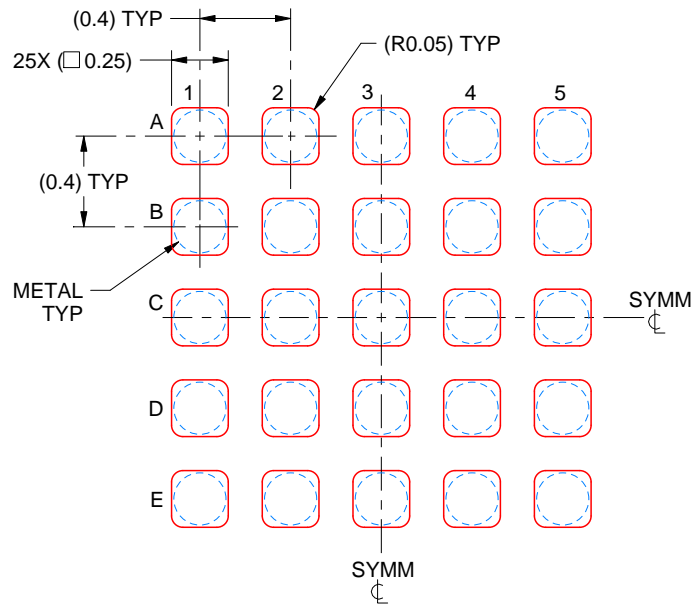
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YFF0025

DSBGA - 0.625 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

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NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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